

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Packaging of components for automatic handling –
Part 3: Packaging of surface mount components on continuous tapes**

**Emballage de composants pour opérations automatisées –
Partie 3: Emballage des composants pour montage en surface en bandes
continues**



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INTERNATIONAL ELECTROTECHNICAL COMMISSION

PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING –**Part 3: Packaging of surface mount components
on continuous tapes**

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IEC 60286-3 has been prepared by IEC technical committee 40: Capacitors and resistors for electronic equipment. It is an International Standard.

This seventh edition cancels and replaces the sixth edition published in 2019. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) addition terms and definitions.
- b) addition of a table of the classification to symbols concerning drive hole diameter and distance between the reel hole centre and the drive hole centre;
- c) addition of drive hole to the reel (optional);
- d) revision of reel hole diameter tolerances;
- e) revision of 72 mm tape size carrier tape width dimension tolerances;

- f) addition of Annex B (informative);
- g) addition of component size 0201M.

The text of this International Standard is based on the following documents:

Draft	Report on voting
40/2972/FDIS	40/2984/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

A list of all parts in the IEC 60268 series, published under the general title *Packaging of components for automatic handling*, can be found on the IEC website.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

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INTRODUCTION

Tape packaging meets the requirements of automatic component placement machines and also covers the use of tape packaging for components and singulated dies for test purposes and other operations.

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PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING –

Part 3: Packaging of surface mount components on continuous tapes

1 Scope

This part of IEC 60286 is applicable to the tape packaging of electronic components without leads or with lead stumps, intended to be connected to electronic circuits. It includes only those dimensions that are essential for the taping of components intended for the above-mentioned purposes.

This document also includes requirements related to the packaging of singulated die products including bare die and bumped die (flip chips).

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60191-2, *Mechanical standardization of semiconductor devices – Part 2: Dimensions*

IEC 61340-4-5, *Electrostatics – Part 4-5: Standard test methods for specific applications – Methods for characterizing the electrostatic protection of footwear and flooring in combination with a person*

IEC 61340-4-6, *Electrostatics – Part 4-6: Standard test methods for specific applications – Wrist straps*

IEC 61340-4-7, *Electrostatics – Part 4-7: Standard test methods for specific applications – Ionization*

IEC 61340-4-9, *Electrostatics – Part 4-9: Standard test methods for specific applications – Garments*

3 Terms, definitions and symbols

3.1 Terms and definitions

For the purposes of this document, the following terms and definitions apply. Definitions apply to all tape types, unless specifically mentioned.

ISO and IEC maintain terminology databases for use in standardization at the following addresses:

- IEC Electropedia: available at <https://www.electropedia.org/>
- ISO Online browsing platform: available at <https://www.iso.org/obp>